

ABSTRACT

The present application discloses a wafer separation method. The wafer separation method comprises: supporting, on a supporting platform, a wafer to be processed in which a pre-crack has formed, a first end surface of the wafer being upward and a cutting tool processing the wafer along a first preset position of the first end surface of the wafer; and adjusting the height of the supporting platform and supporting the wafer on the supporting platform again, a second end surface of the wafer being upward and the cutting tool processing the wafer along a second preset position of the second end surface of the wafer, to complete processing of the wafer. The wafer separation method of the present application avoids mechanical deformation and stress concentration release caused by mechanical processing and splitting of wafers, eliminates cutting tool wear and dust pollution, and does not require wafers to be cleaned with pure water, thereby eliminating wastewater generation and saving costs. The present application further provides a wafer processing apparatus.